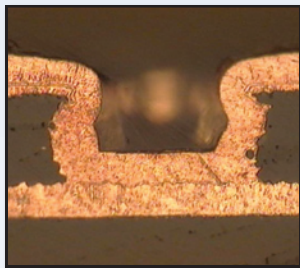
DC Copper Plating for Thick Panel
厚板高縱橫比電鍍銅技術

Next Generation of Thick Panel Copper Plating Technology

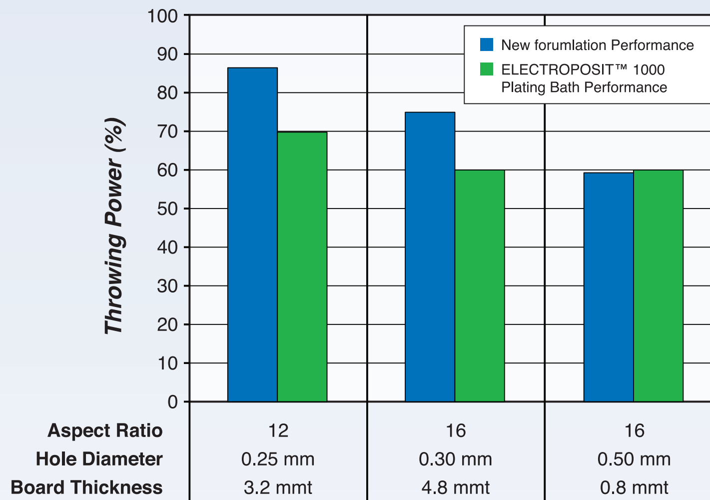
A latest technology is under developed for thick panel plating, which provides better throwing power under a basis of 10~20% higher current density than existing product. Obviously, it helps to increase plating efficiency and obtainable higher productivity without any required equipment investment.

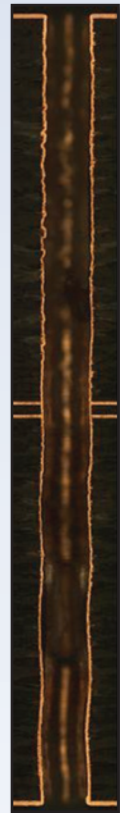
陶氏化學電子材料，最新一代的厚板電鍍技術正在開發中。在相對於現有產品高於10~20%電流密度的基礎下，它將能提供較佳的通孔貫孔能力。顯而易見的，它有助提高電鍍效率與產能且不需任何設備的額外投資。

- High throwing power
  高通孔貫孔能力
  - at higher plating current density
    於較高電流密度下
  - on high aspect ratio boards
    於高縱橫度板
  - on microvia
    於微盲孔電鍍
- Microvia plating capability
  可同時兼顧微盲孔電鍍
- Full analysis system by CVS
  可使用 CVS分析所有添加劑
- Excellent thermal reliability
  優越的熱信賴度



Via diameter: 6 mil
Via deep: 4 mil
Aspect Ratio: 0.67:1
CD: 12 ASF





Hole diameter: 0.5 mm
Panel thickness: 8 mm
Aspect Ratio: 16:1
CD: 12 ASF

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